100 Gb/s per Lane for Electrical Interfaces and PHYs CFI Consensus Building

CFI Target: IEEE 802.3 November 2017 Plenary

Objective

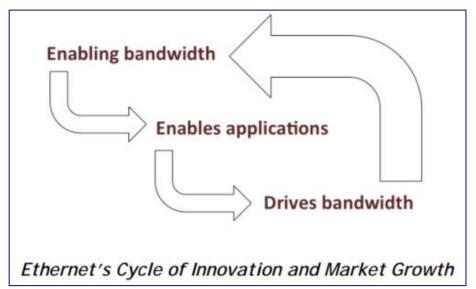
- Build consensus of starting a study group investigating a "100 Gb/s per lane for electrical interfaces and PHYs" project
- We do **not** need to:
 - Fully explore the problem
 - Debate strengths and weaknesses of solutions
 - Choose a solution
 - Create a PAR or 5 Criteria
 - Create a standard
- Anyone in the room may vote or speak

Motivation for 100 Gb/s per Lane

With next steps in Ethernet, comes the needed next step in interfaces.

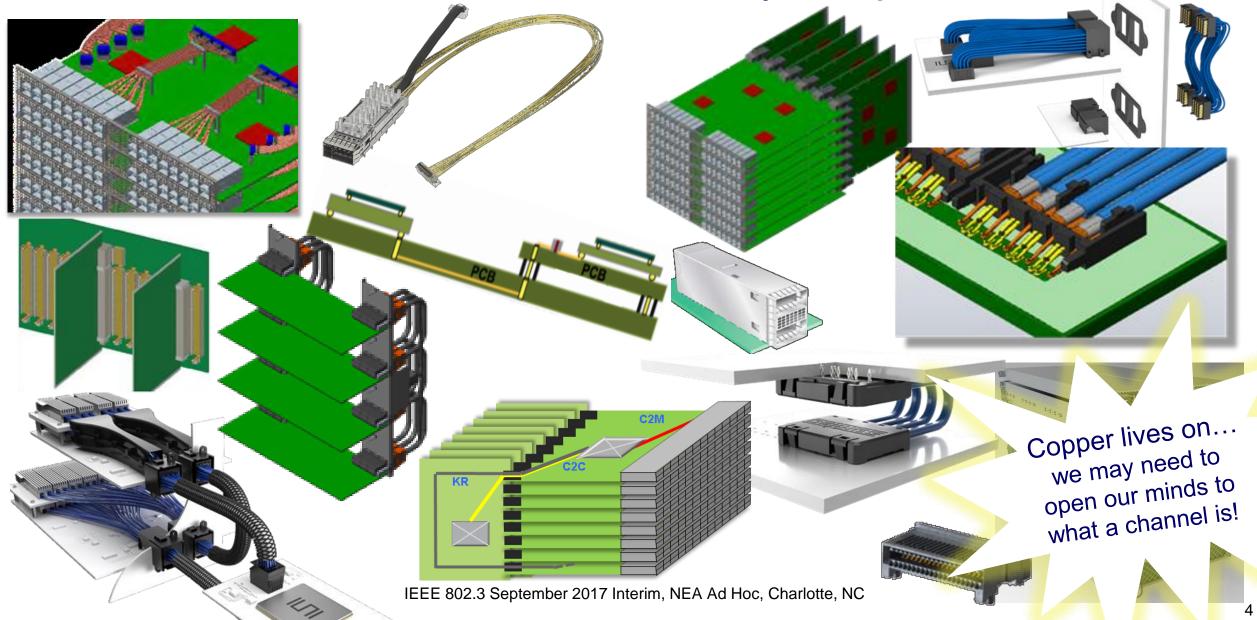
- Faceplate density
- Chip breakout
- System throughput

They are all tied together!



*Web-scale data centers and cloud based service are presented as leading applications

Electrical interfaces come in many shapes and sizes.



Tonight's Meeting

• To present the

market **NEED**, technical **Feasibility**,

and *Why Now??*

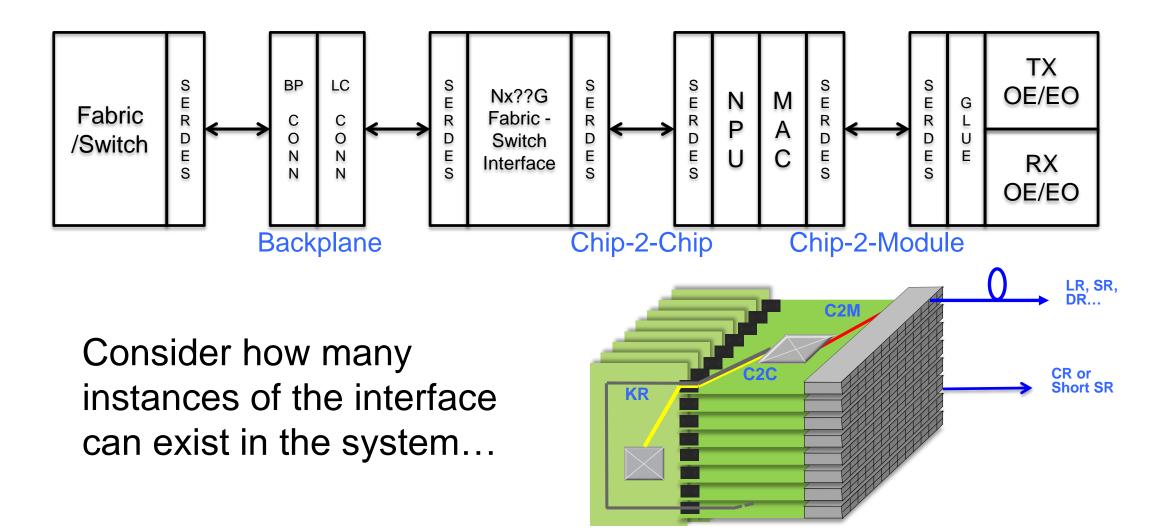
of 100Gb/s per lane of electrical signaling.

- To gain consensus towards Thursday's Call-for-Interest.
- We are NOT discussing specific implementations or objectives these are just some of the reasons that we <u>need</u> a study group!

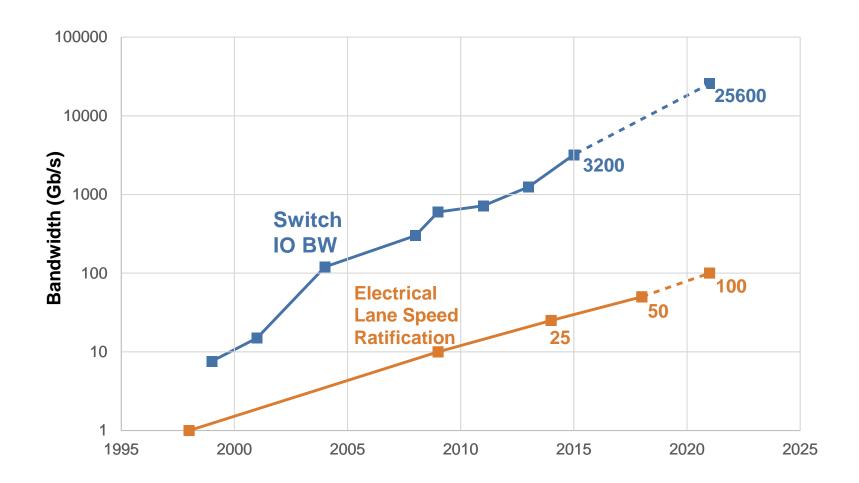
Market Drivers for 100 Gb/s per lane for Electrical Interfaces

Go Faster to Go **Denser** to Continue to **Grow**.

What Are We Talking About?



Historical Perspective Shows What's Coming

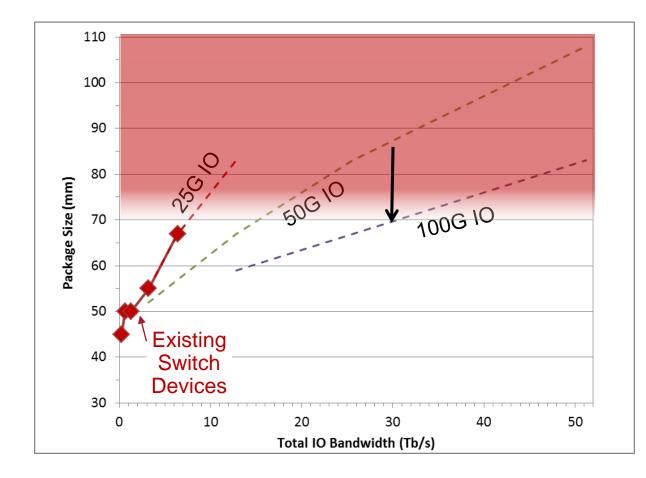


Historical curve fit to highest rate switch products introduced to market (blue squares)

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Single ASIC IO capacity doubling every ~ 2 years

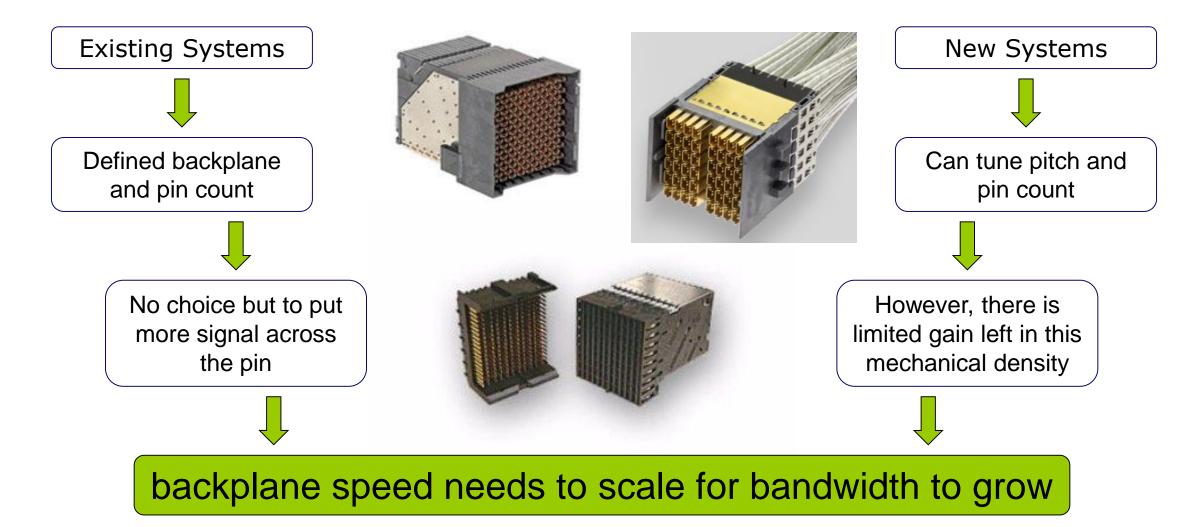
IO Escape forcing transition to higher lane speeds



- ~ 70mm package is a current BGA practical maximum (due to coplanarity / warpage)
- This will force BGA devices with > 14Tb/s of aggregate bandwidth to transition to lane rates of higher greater than 50G (possibly 100G?)

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Backplane is easily system bottleneck



The Current Ethernet Family (100 Gb/s and Above)

	Signaling (Gb/s)	Electrical Interface	Backplane	Twin- ax	MMF	500m SMF	2km SMF	10km SMF	40km SMF
100GBASE-	10	CAUI-10		CR10	SR10		<u>10X10</u>		
	25	CAUI-4 / 100GAUI-4	KR4	CR4	SR4	PSM4	CWDM4 CLR4	LR4	ER4
	50	100GAUI-2	KR2	CR2	SR2		_		
	100	?	?	?		DR			
200GBASE-	25	200GAUI-8							
	50	200GAUI-4	KR4	CR4	SR4	DR4	FR4	LR4	
	100	?	?	?					
400GBASE-	25	400GAUI-16			SR16				
	50	400GAUI-8					FR8	LR8	
	100	?	?	?		DR4			

Includes Ethernet standards in development

<u>Underlined</u> – indicates industry MSA or proprietary solutions

Blue - indicates the areas of interest for this CFI

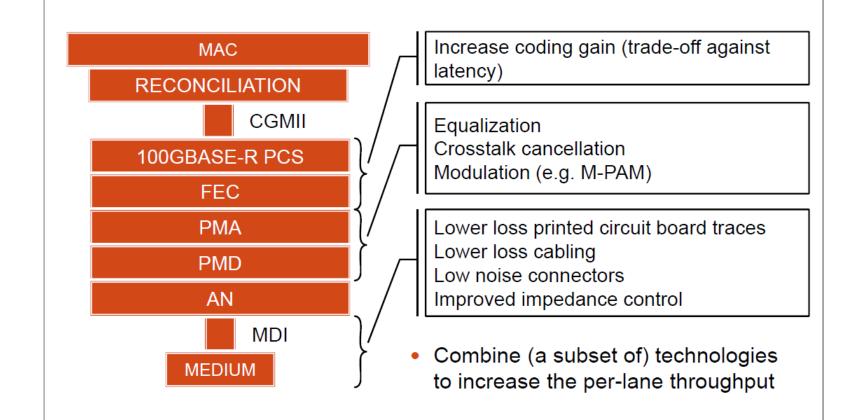
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Technical Feasibility for 100 Gb/s per lane for Electrical Interfaces

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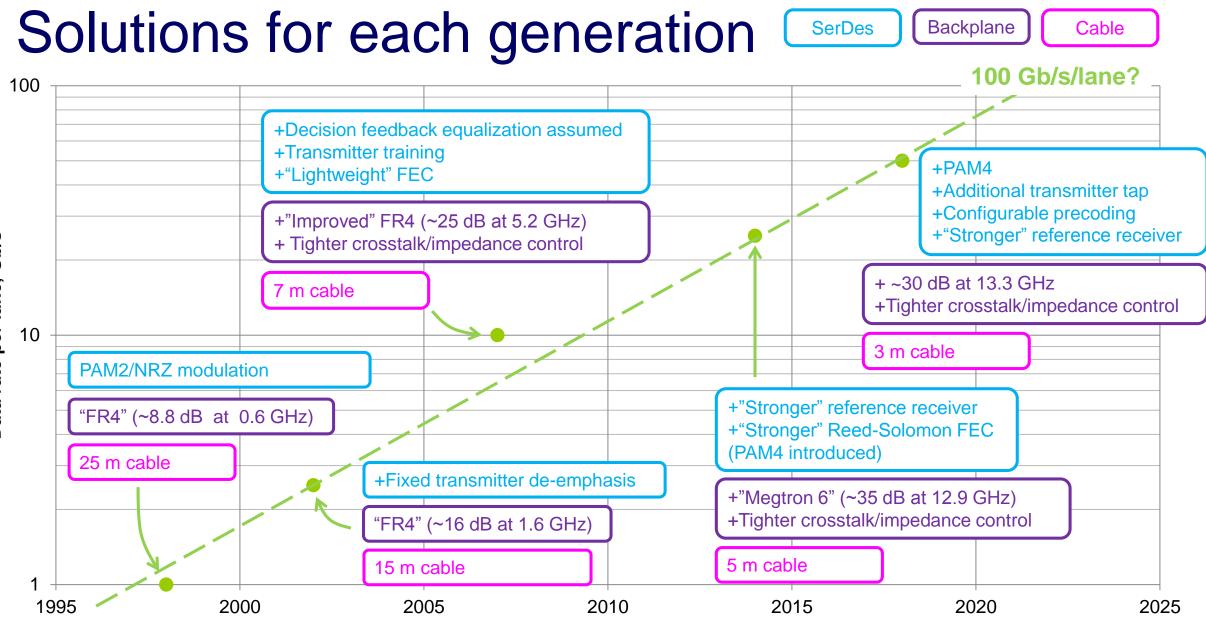
It's time to open the toolbox again...





From the <u>100GbE Electrical Backplane / Cu Cabling Call-For-Interest</u> consensus building presentation, November 2010

November 9, 2010



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Different constraints for different applications

Chip-to-module

- "Coexistence" with defined PHYs, FEC, PCS?
- What is the minimum insertion loss that supports useful topologies?
- Consider improved PCB materials, PCB vs. cable, improvements in impedance/noise control?

Chip-to-chip and "backplane"

- What is the minimum insertion loss that support useful topologies?
- Consider improved PCB materials, PCB vs. cable, improvements in impedance/noise control?

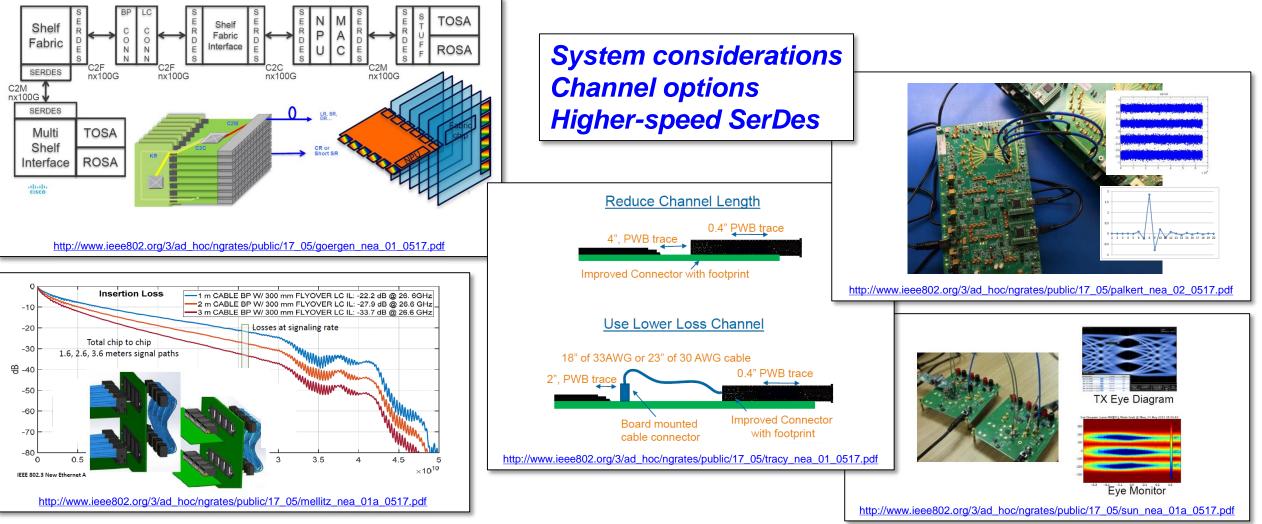
<u>Cable</u>

- What is the minimum useful reach?
- Consider "middle-of-rack" topologies?

Apply signal processing to meet the needs of each application

The discussion is already underway

From the proceedings of the IEEE 802.3 New Ethernet Applications ad hoc



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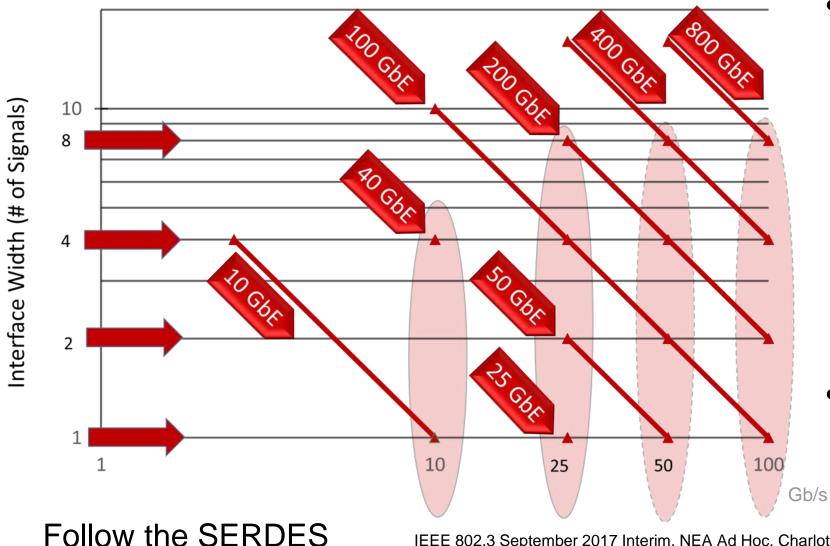
Technical feasibility summary

- Rich signal integrity and signal processing toolbox that can be applied to the problem of "100 Gb/s per lane electrical signaling"
- We must be mindful of the different needs for different applications
- We have done this many times before
- The discussion is already underway



Why Now??? 100 Gb/s per lane of Electrical Interfaces

The Road Map of Port Rates - next logical step



- 100G/lane is coming...
 - 100G/lane optics are here
 - OIF/Inifinband are working on this
- We need study and frame it NOW so the industry can plan

The Interest is Here

Straw Poll #2

- Is there interest in developing AUI's based on 100 Gb/s electrical signaling per lane? ٠
- Results .
 - Yes 43
 - No 2
 - Maybe 15 .

Straw Poll #3

- Is there interest in developing Backplane / Copper Cable PHYs based on 100 Gb/s electrical signaling per lane?
 - Yes 18
 - No 10
 - Maybe 20

March 2017**

Straw Polls

Taken from NEA Ad Hoc unapproved Minutes

- * http://www.ieee802.org/3/ad hoc/ngrates/public/17 05/minutes nea 0517 unapproved.pdf
- ** http://www.ieee802.org/3/ad hoc/ngrates/public/17 03/minutes nea 0317 unapproved.pdf

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Straw Poll #1

I would support development of a CFI that includes: .

20

- a) new backplane PHY,
- b) new Passive Copper Cable PHY
- c) Chip-to-chip (C2C AUI)
- Chip-to-module (C2M AUI)
- e) other

32

26

40

48

0

2

0

- not at this time,
- a) none of the above
- Results

a)

b)

C)

d)

e)

g)

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Summary

- 100 Gb/s is the next step on "Follow the SerDes" and continues existing market trends
- We've moved to the "unknown" before and the industry survived.
- Technical details need to be rebalanced for the next speed.
- Impact of 100 Gb/s Electrical Signaling is wide across the Ethernet Family
- Let's form a Study Group!!

Thank You!

Go Faster to Go **Denser** to Continue to **Grow**.